COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE  BOARD #: TIDA-01472  REV: E1  SUN REV: Not In VersionControl
TID #: TIDA-01472
PLDT NAME = Bottom Assembly Drawing  GENERATED : 5/11/2017 10:14:04 AM  TEXAS INSTRUMENTS
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